OIPE IAP84
JUN 17 2008
PATENT & TRADEMARK OFFICE

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re U.S. Patent Application of:

APPLICANT: C. Kim et al.

SERIAL NO.: 10/678,655 EXAMINER: Ip, Sikyin

FILING DATE: October 2, 2003 ART UNIT: 1793

ATTORNEY'S DOCKET NO.: 873.0125.U1(US)

TITLE: Lead-Free Solder Alloys And Methods Of Making Same

MAIL STOP Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT IN RESPONSE TO OFFICE ACTION

Sir:

This paper is herewith filed in response to the Examiner's Office Action mailed on May 16, 2008 for the above-captioned U.S. Patent Application. No fee is believed to be required in conjunction with the submission of this paper. However, should the undersigned attorney be mistaken, please consider this a petition for any extension of time that may be required to maintain the pendency of this Patent Application, and charge deposit account no.: 50-1924 for any required fee deficiency.

Please amend the claims as set forth below. The below claim set is a complete listing of the claims and replaces all prior versions.